

Docket #: S03-235

Thermal Interface Materials

Applications

- Promote heat flow from a heat-generating device to its cooling components
- Release thermal expansion mismatch

Advantages

- Higher thermal conductivity
- Lower interface thermal resistance
- Compatible usage with traditional thermal interface materials

Publications

- Hu, X., Jiang, L., and Goodson, K.E., "Thermal Conductance Enhancement of Particle-Filled Thermal Interface Materials using Carbon Nanotube Inclusions", Thermal and Thermomechanical Phenomena in Electronic Systems, 1-4 June 2004, pages 63 - 69 Vol.1.

Patents

- Published Application: [20050171269](#)

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